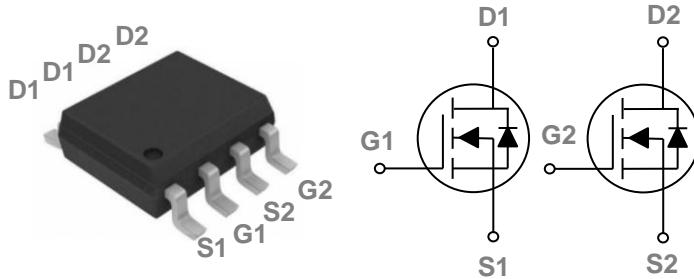


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### SOP8 Dual Pin Configuration



BVDSS	RDS(ON)	ID
60V	30mΩ	5A

### Features

- 60V, 5A, RDS(ON) = 30mΩ@VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- Motor Drive
- Power Tools
- LED Lighting

### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_A=25^\circ\text{C}$ )	5	A
	Drain Current – Continuous ( $T_A=70^\circ\text{C}$ )	4	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	20	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	26.5	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	23	A
$P_D$	Power Dissipation ( $T_A=25^\circ\text{C}$ )	1.47	W
	Power Dissipation – Derate above 25°C	0.012	W/°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	85	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=250\mu\text{A}$	60	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=1\text{mA}$	---	0.06	---	$\text{V}/^\circ\text{C}$
$I_{\text{DS}}^{\text{SS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=60\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=48\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA

**On Characteristics**

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=4\text{A}$	---	24	30	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_{\text{D}}=3\text{A}$	---	29	38	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=250\mu\text{A}$	1.2	1.7	2.5	V
			---	-4.6	---	$\text{mV}/^\circ\text{C}$
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_{\text{D}}=3\text{A}$	---	7	---	S

**Dynamic and switching Characteristics**

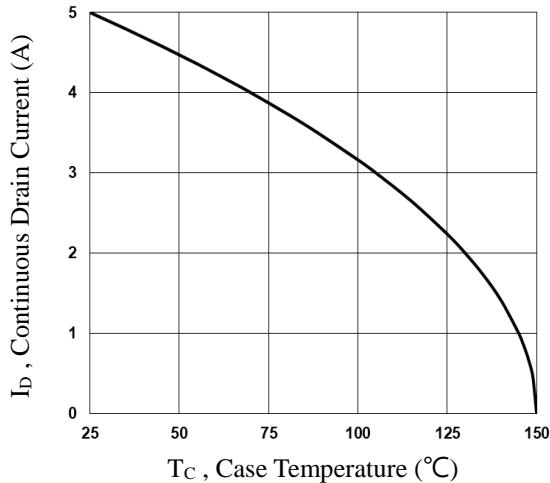
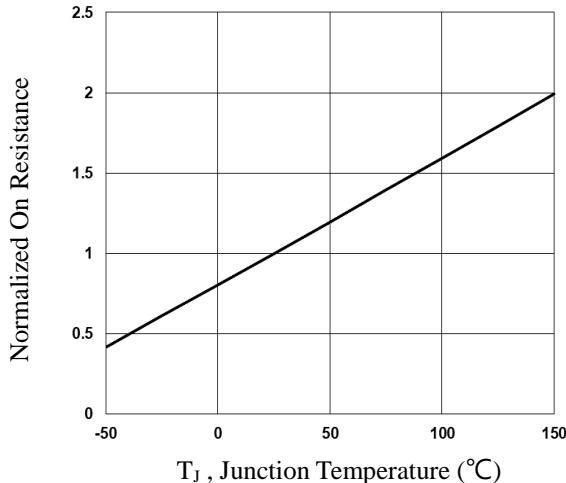
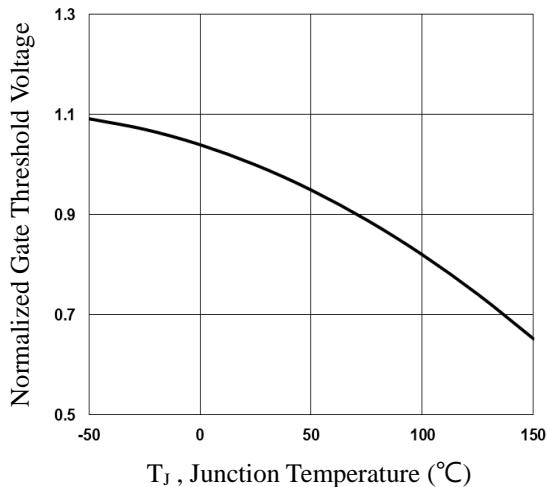
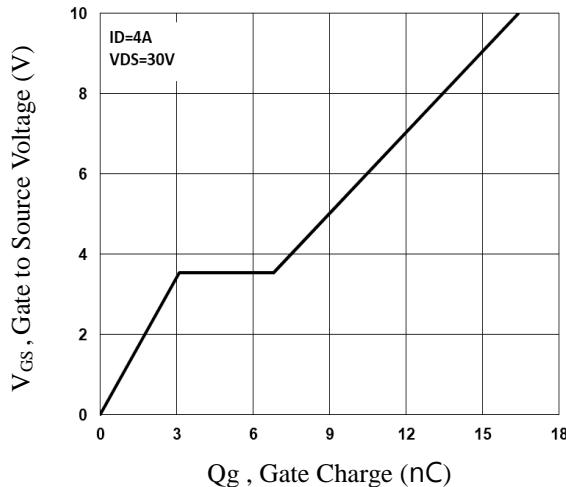
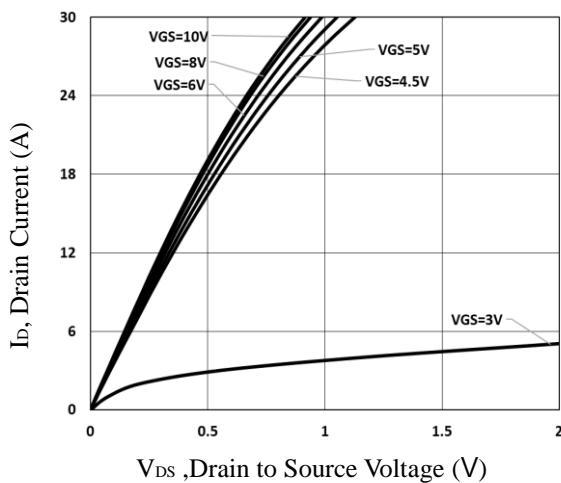
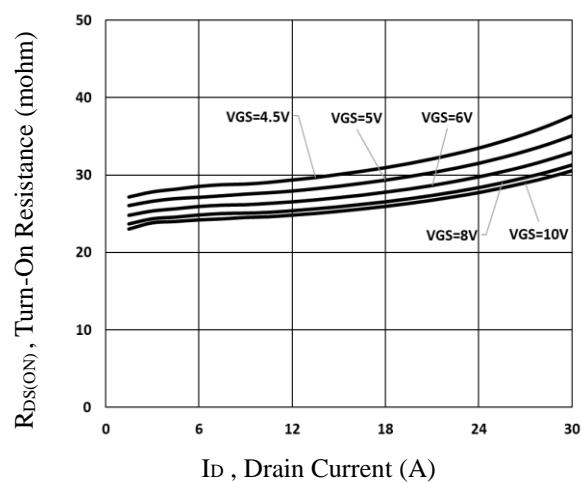
$Q_g$	Total Gate Charge <sup>2, 3</sup>	$V_{\text{DS}}=30\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=4\text{A}$	---	16.6	24	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>2, 3</sup>		---	2.2	4.4	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>2, 3</sup>		---	3.9	8	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>2, 3</sup>	$V_{\text{DD}}=30\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_{\text{G}}=6\Omega$	---	4.6	9	ns
$T_r$	Rise Time <sup>2, 3</sup>		---	14.8	28	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>2, 3</sup>		---	27.2	52	
$T_f$	Fall Time <sup>2, 3</sup>		---	7.8	15	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=30\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	1180	1720	pF
$C_{\text{oss}}$	Output Capacitance		---	68	100	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	45	70	
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $F=1\text{MHz}$	---	2.1	4.2	$\Omega$

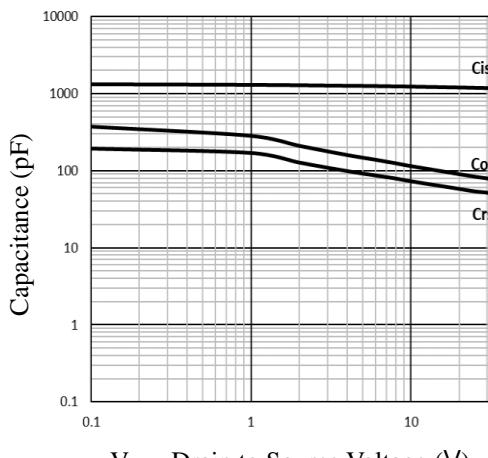
**Drain-Source Diode Characteristics and Maximum Ratings**

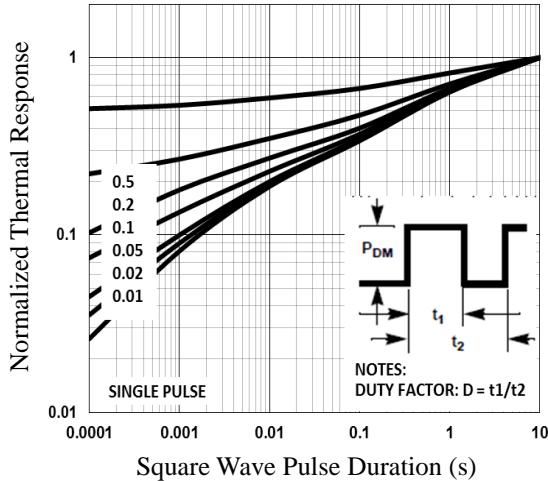
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	5	A
			---	---	10	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V
$t_{\text{rr}}$	Reverse Recovery Time <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=10\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$	---	23	---	ns
			---	13	---	nC

Note :

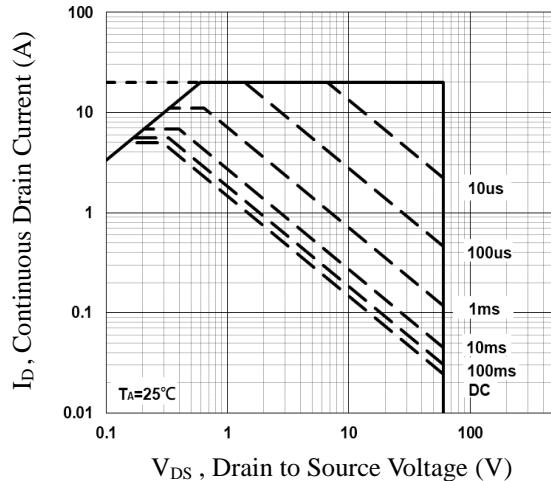
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{\text{DD}}=50\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=23\text{A}$ ,  $R_{\text{G}}=25\Omega$ , Starting  $T_J=25^\circ\text{C}$
3. The data tested by pulsed, pulse width  $\leq 300\text{us}$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

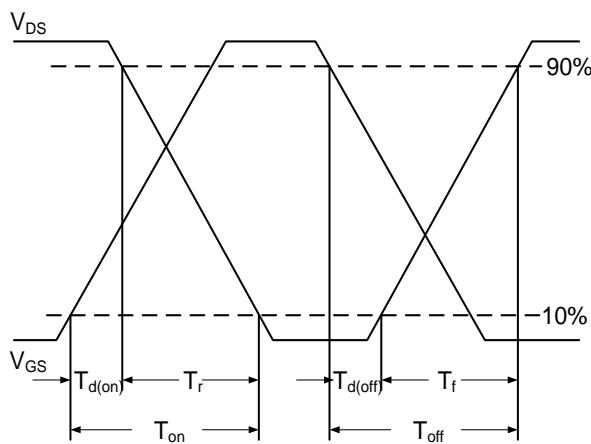
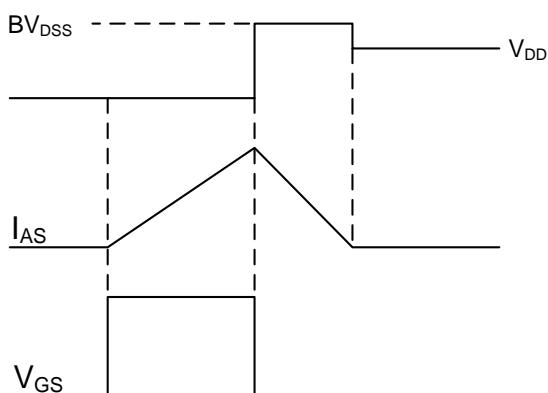

**Fig.1 Continuous Drain Current vs. Tc**

**Fig.2 Normalized RDSON vs. Tj**

**Fig.3 Normalized Vth vs. Tj**

**Fig.4 Gate Charge Waveform**

**Fig.5 Typical Output Characteristics**

**Fig.6 Turn-On Resistance vs. Id**


 V<sub>DS</sub>, Drain to Source Voltage (V)

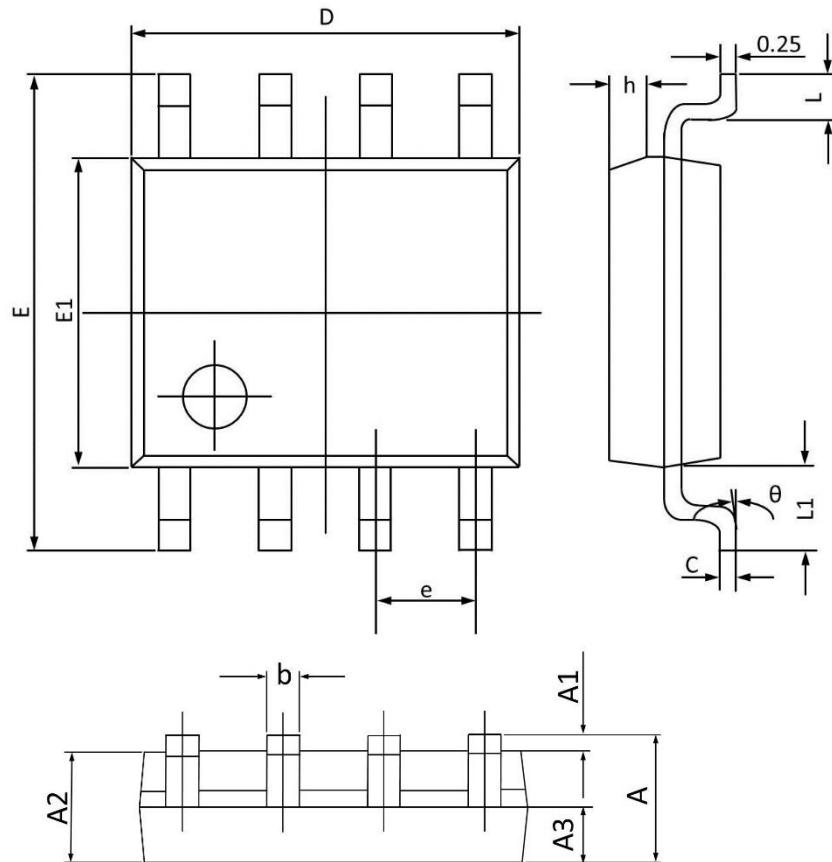
**Fig.7 Capacitance Characteristics**


Square Wave Pulse Duration (s)

**Fig.8 Normalized Transient Impedance**

 V<sub>DS</sub>, Drain to Source Voltage (V)

**Fig.9 Maximum Safe Operation Area**

**Fig.10 Switching Time Waveform**

**Fig.11 EAS Waveform**

## SOP8 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.800	0.053	0.069
A1	0.050	0.250	0.002	0.010
A2	1.250	1.650	0.049	0.065
A3	0.500	0.700	0.020	0.028
b	0.300	0.510	0.012	0.020
c	0.150	0.260	0.006	0.010
D	4.700	5.100	0.185	0.201
E	5.800	6.200	0.228	0.244
E1	3.700	4.100	0.146	0.161
e	1.270(BSC)		0.050(BSC)	
h	0.250	0.500	0.010	0.020
L	0.400	1.000	0.016	0.039
L1	1.050(BSC)		0.041(BSC)	
θ	0°	8°	0°	8°